



Material Content Data Sheet



Sales Product Name	SAK-XC2320D-12F66V AA			Issued		29. August 2013		
MA#	MA001105472							
Package	PG-VQFN-48-54			Weight*		126.41 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.350	4.23	4.23	42325	42325
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		140	
	non noble metal	zinc	7440-66-6	0.071	0.06		558	
	non noble metal	iron	7439-89-6	1.412	1.12		11168	
	non noble metal	copper	7440-50-8	57.319	45.35	46.54	453452	465318
wire	noble metal	gold	7440-57-5	0.733	0.58	0.58	5802	5802
encapsulation	organic material	carbon black	1333-86-4	0.172	0.14		1359	
	plastics	epoxy resin	-	7.271	5.75		57522	
	inorganic material	silicondioxide	60676-86-0	49.810	39.40	45.29	394048	452929
leadfinish	non noble metal	tin	7440-31-5	2.340	1.85	1.85	18515	18515
plating	noble metal	silver	7440-22-4	0.656	0.52	0.52	5189	5189
glue	plastics	epoxy resin	-	0.288	0.23		2282	
	noble metal	silver	7440-22-4	0.966	0.76	0.99	7640	9922
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

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